

# PA NT ABSTRACTS OF JAPAN

(11)Publication number : 11-261216  
(43)Date of publication of application : 24.09.1999

(51)Int.CI. H05K 3/40  
H05K 3/46

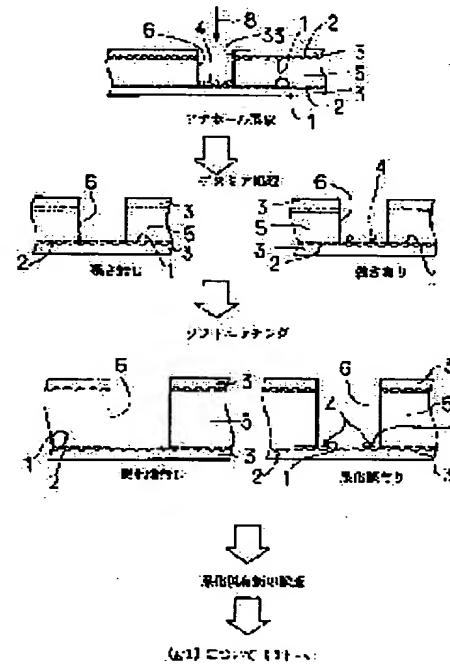
(21)Application number : 10-076734 (71)Applicant : IBIDEN CO LTD  
(22)Date of filing : 09.03.1998 (72)Inventor : KONDO MITSUHIRO  
TSUKADA KIYOTAKA

## (54) PRINTED WIRING BOARD AND ITS MANUFACTURE

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a printed wiring board with via holes having high continuity reliability and a method for manufacturing the board.

**SOLUTION:** After a blackened film 1 is formed by blackening metal foil 3, the metal foil 3 is stuck to the bottom of the via hole-forming section of an insulating substrate 5 in a state where the blackened film 1 is faced to the bottom. Then a via hole 6 bottomed with the metal foil 3 is formed by irradiating the substrate 5 with a laser beam 8 and desmearing treatment is performed on the foil 3 exposed at the bottom of the via hole. In addition, soft etching is performed on the plated metallic film exposed at the bottom of the via hole. Thereafter, a plated metallic film is formed in the via hole after confirming that the blackened film 1 is removed by the soft etching from the surface of the foil 3 at the bottom of the via hole and a conductor pattern is formed by etching the foil 3.



## LEGAL STATUS

[Date of request for examination] 05.03.2001

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]